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MARKED-UP VERSION OF AMENDED CLAIMS

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JUL -8 2002
TECHNOLOGY CENTER 2800

1. (Amended) A wiring substrate equipped with a rerouted wiring having one end connected to an electronic-part mounting pad for electrically connecting an electronic part and another end connected to an external-connection terminal, in which [a base body of] said wiring substrate comprises a base body having selectively formed thereon a low-elasticity underlayer, made of a material having a lower modulus of elasticity than that of the base body [material], in a pattern that the external-connection terminal is exposed in a surface of the base body, said underlayer being positioned between the base body [material] of the wiring substrate and each of the electronic-part mounting pad and the rerouted wiring.

12. (Amended) A semiconductor device comprising a wiring substrate equipped with a rerouted wiring having one end connected to an electronic-part mounting pad for electrically connecting an electronic part and another end connected to an external-connection terminal, and an electronic part electrically connected and mounted on the pad of the wiring substrate, in which [a base body of] said wiring substrate comprises a base body having selectively formed thereon a low-elasticity underlayer, made of a material having a lower modulus of elasticity than that of the base body [material], in a pattern

that the external-connection terminal is exposed in a surface of
the base body, said underlayer being positioned between the base
body [material] of the wiring substrate and each of the
electronic-part mounting pad and the rerouted wiring.